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**DEC 20 2005****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of  
**Venkateswaran et al.**

Docket Number: **TI-36587**Serial No.: **10/748,023**Art Unit: **2826**Filed: **12/30/2003**Examiner: **L. Andujar**For: **FORMING A CHIP PACKAGE HAVING A NO-FLOW UNDERFILL****CERTIFICATION OF FACSIMILE TRANSMISSION**

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NAME OF INVENTOR(S): <b>VENKATESWARAN</b>		RECEIPT DATE & SERIAL NO.: Serial No.: <b>10/748,023</b>
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